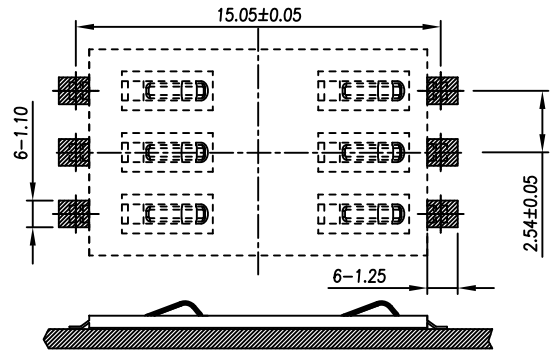
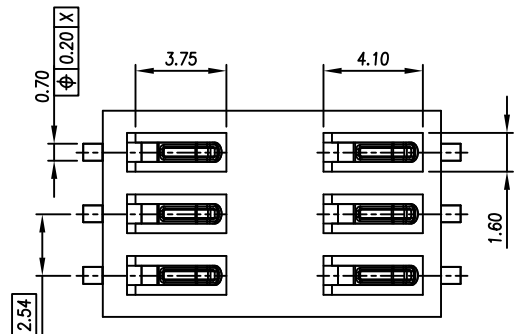
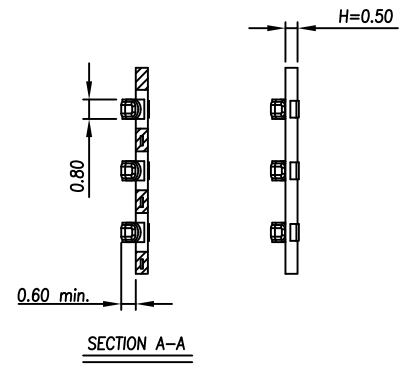
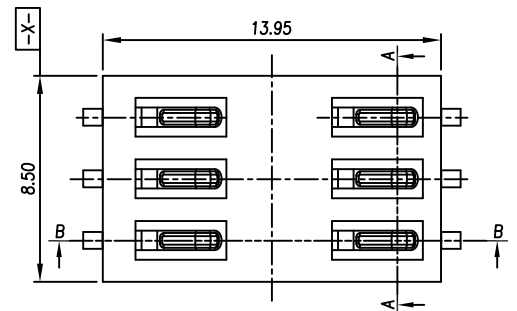


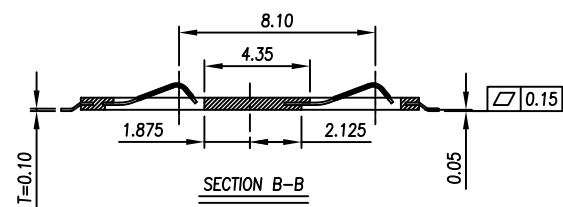
REV	MODIFICATION	DATE	DRAW
E	EN-06-0802	95/08/01	TERENCE
F	EN-07-1037	96/10/31	SAN
G	ECN2-00000532	2017.08.18	Moya



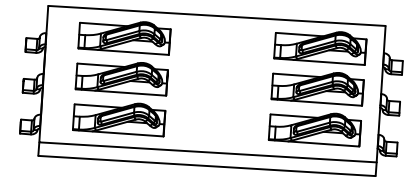
P.C.B. LAYOUT (TOP VIEW)



SECTION A-A



SECTION B-B



NOTES:

- Material :
Housing : Thermoplastic UL94V-0
Contact : BERYLLIUM C17200R-H,T=0.10mm.
- Plating :
Contact Plating - Gold over 45u" MIN.Nickel
Solder Tail Plating - Gold Flash over 45u" MIN.Nickel
- Contact Forces :
Max. 0.5 N For 0.5mm Contact Deflection.
Min. 0.25 N For 0.5mm Contact Deflection.
- Specification :
Withstanding Voltage:500V AC initial and 250 V AC final at sea level for 1 Minute
Insulation Resistance:1000M Ohms
Voltage Rating:5 Volts Max
Current Rating:10mA Max
Contact Resistance:30m Ohms Max
Operating Temperature:-40°C~+85°C
Insertion Cycles:20,000 Times
- Application:
For SIM Card Use Only
- Order Information :
2SIMMP-00603BTx1
03 : GOLD PLATING 03u". 0 : TAPE REEL
1 : TUBE

TOLERANCE UNLESS OTHERWISE SPECIFIED		Singatron Enterprise Co., Ltd.		
.X±0.30	X.*± 1*	TITLE	Subscriber Identify Module Card Simple Style Conn. 6 Pin Same Direction Type 0.50mm	
.XX±0.20	.X.*± 0.5*	DWN	PART NO. 2SIMMP-00603BTx1	
.XXX±0.10	.XX.*± 0.25*	CHKD	SCALE 1:1	UNIT: mm
		APVD	SIZE: A3	SHEET:1 OF 1 REV: G
CUSTOMER COPY				